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(54) Title: ATOMIC LAYER PROCESS PRINTER

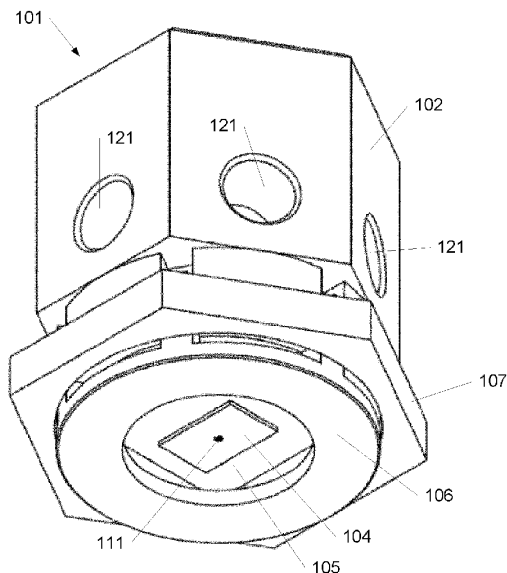


Fig. 3A

(57) Abstract: The invention relates to an atomic layer process printer for material deposition, etching and/or cleaning on an atomic scale in a selective area. The invention further relates to a method for material deposition, etching and/or cleaning on an atomic scale in a selective area using the atomic layer process printer.

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